



Click [here](#) for the 3D model.

| Dimensions | |
|------------|---------------------|
| D | 6.3mm +/-0.5mm |
| L | 7.7mm +/-0.3mm |
| W | 0.65mm +/-0.1mm |
| F | 0.3mm MAX |
| A | 6.6mm +/-0.2mm |
| B | 6.6mm +/-0.2mm |
| C | 7.8mm MAX |
| E | 2.6mm +/-0.2mm |
| G | 0.35mm +0.15/-0.2mm |
| P | 1.8mm +/-0.2mm |

| Packaging Specifications | |
|--------------------------|------------|
| Packaging | T&R, 380mm |
| Packaging Quantity | 1000 |

| General Information | |
|---------------------|--------------------------------------|
| Series | EXV |
| Dielectric | Aluminum Electrolytic |
| Style | SMD Can |
| Description | Surface Mount, Aluminum Electrolytic |
| Features | Ultra Low Impedance |
| RoHS | Yes |
| Lead | V-Chip |
| AEC-Q200 | No |

| Specifications | |
|-------------------------|--|
| Capacitance | 100 uF |
| Capacitance Tolerance | 20% |
| Voltage DC | 25 VDC, 32 VDC (Surge) |
| Temperature Range | -55/+105°C |
| Rated Temperature | 105°C |
| Life | 3000 Hrs |
| Dissipation Factor | 14% |
| Resistance | 0.34 Ohms (100kHz) |
| Ripple Current | 210 mAmps (120Hz), 420 mAmps (120Hz 85C), 300 mAmps (100kHz) |
| Leakage Current | 25 uA (2min 20°C) |
| Impedance Ratio at -25C | 2 |
| Impedance Ratio at -40C | 3 |
| High Temperature Solder | Yes |